

MC74LCX74

Low-Voltage CMOS Dual D-Type Flip-Flop

With 5 V-Tolerant Inputs

The MC74LCX74 is a high performance, dual D-type flip-flop with asynchronous clear and set inputs and complementary (O, \bar{O}) outputs. It operates from a 2.3 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A V_I specification of 5.5 V allows MC74LCX74 inputs to be safely driven from 5.0 V devices.

The MC74LCX74 consists of 2 edge-triggered flip-flops with individual D-type inputs. The flip-flop will store the state of individual D inputs, that meet the setup and hold time requirements, on the LOW-to-HIGH Clock (CP) transition.

Features

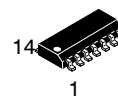
- Designed for 2.3 V to 3.6 V V_{CC} Operation
- 5.0 V Tolerant Inputs – Interface Capability With 5.0 V TTL Logic
- LVTTL Compatible
- LVC MOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current in All Three Logic States (10 μ A) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance: Human Body Model >2000 V
Machine Model >200 V
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant



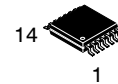
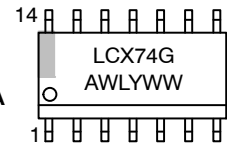
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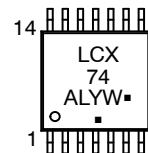
MARKING DIAGRAMS



SOIC-14
D SUFFIX
CASE 751A



TSSOP-14
DT SUFFIX
CASE 948G



A = Assembly Location
L, WL = Wafer Lot
Y, YY = Year
W, WW = Work Week
G or ▪ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

MC74LCX74

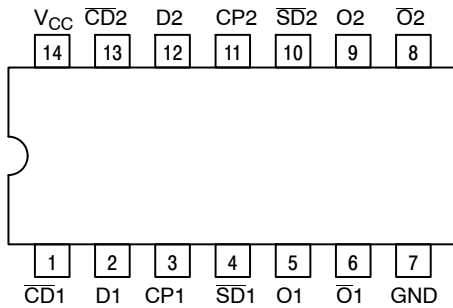


Figure 1. Pinout: 14-Lead (Top View)

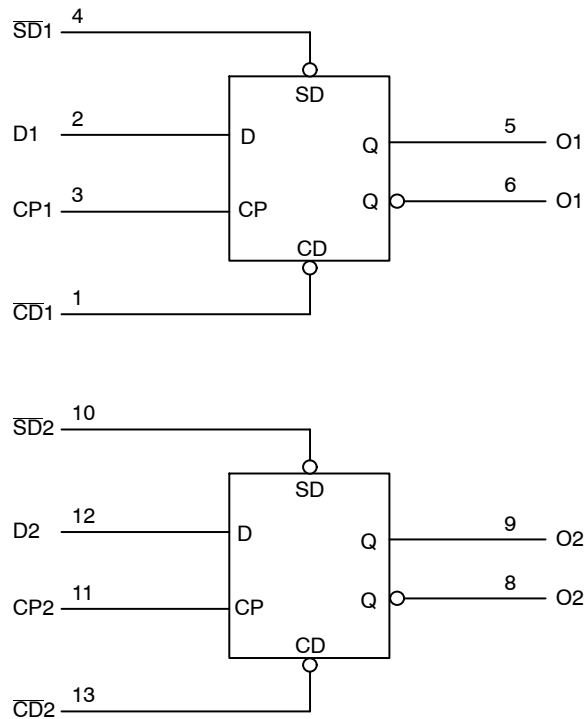


Figure 2. Logic Diagram

PIN NAMES

| Pins | Function |
|----------|---------------------|
| CP1, CP2 | Clock Pulse Inputs |
| D1-D2 | Data Inputs |
| CD1, CD2 | Direct Clear Inputs |
| SD1, SD2 | Direct Set Inputs |
| On-ON | Outputs |

TRUTH TABLE

| Inputs | | | | Outputs | | Operating Mode |
|--------|-----|-----|----|---------|----|------------------------|
| SDn | CDn | CPn | Dn | On | ON | |
| L | H | X | X | H | L | Asynchronous Set |
| H | L | X | X | L | H | Asynchronous Clear |
| L | L | X | X | H | H | Undetermined |
| H | H | ↑ | h | H | L | Load and Read Register |
| H | H | ↑ | l | L | H | |
| H | H | ‡ | X | NC | NC | Hold |

- H = High Voltage Level
- h = High Voltage Level One Setup Time Prior to the Low-to-High Clock Transition
- L = Low Voltage Level
- l = Low Voltage Level One Setup Time Prior to the Low-to-High Clock Transition
- NC = No Change
- X = High or Low Voltage Level and Transitions are Acceptable
- ↑ = Low-to-High Transition
- ‡ = Not a Low-to-High Transition

For I_{CC} reasons, DO NOT FLOAT Inputs

MC74LCX74

MAXIMUM RATINGS

| Symbol | Parameter | Value | Condition | Units |
|------------------|----------------------------------|---|--------------------------------------|-------|
| V _{CC} | DC Supply Voltage | -0.5 to +7.0 | | V |
| V _I | DC Input Voltage | -0.5 ≤ V _I ≤ +7.0 | | V |
| V _O | DC Output Voltage | -0.5 ≤ V _O ≤ V _{CC} + 0.5 | Output in HIGH or LOW State (Note 1) | V |
| I _{IK} | DC Input Diode Current | -50 | V _I < GND | mA |
| I _{OK} | DC Output Diode Current | -50 | V _O < GND | mA |
| | | +50 | V _O > V _{CC} | mA |
| I _O | DC Output Source/Sink Current | ±50 | | mA |
| I _{CC} | DC Supply Current Per Supply Pin | ±100 | | mA |
| I _{GND} | DC Ground Current Per Ground Pin | ±100 | | mA |
| T _{STG} | Storage Temperature Range | -65 to +150 | | °C |
| MSL | Moisture Sensitivity | | Level 1 | |

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. I_O absolute maximum rating must be observed.

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | Min | Type | Max | Units |
|-----------------|--|-----|----------|-----------------|-------|
| V _{CC} | Supply Voltage Operating Data Retention Only | 2.0 | 2.5, 3.3 | 3.6 | V |
| | | 1.5 | 2.5, 3.3 | 3.6 | |
| V _I | Input Voltage | 0 | | 5.5 | V |
| V _O | Output Voltage (HIGH or LOW State) | 0 | | V _{CC} | V |
| I _{OH} | HIGH Level Output Current V _{CC} = 3.0 V – 3.6 V V _{CC} = 2.7 V – 3.0 V V _{CC} = 2.3 V – 2.7 V | | | -24 | mA |
| | | | | -12 | |
| | | | | -8 | |
| I _{OL} | LOW Level Output Current V _{CC} = 3.0 V – 3.6 V V _{CC} = 2.7 V – 3.0 V V _{CC} = 2.3 V – 2.7 V | | | +24 | mA |
| | | | | +12 | |
| | | | | +8 | |
| T _A | Operating Free-Air Temperature | -40 | | +85 | °C |
| Δt/ΔV | Input Transition Rise or Fall Rate, V _{IN} from 0.8 V to 2.0 V, V _{CC} = 3.0 V | 0 | | 10 | ns/V |

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|----------------|-----------------------|-----------------------|
| MC74LCX74DG | SOIC-14 (Pb-Free) | 55 Units / Rail |
| MC74LCX74DR2G | SOIC-14 (Pb-Free) | 2500 Tape & Reel |
| MC74LCX74DTG | TSSOP-14 (Pb-Free) | 96 Units / Rail |
| MC74LCX74DTR2G | TSSOP-14 (Pb-Free) | 2500 Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MC74LCX74

DC ELECTRICAL CHARACTERISTICS

| Symbol | Characteristic | Condition | T _A = -40°C to +85°C | | Units |
|------------------|---------------------------------------|--|---------------------------------|------|-------|
| | | | Min | Max | |
| V _{IH} | HIGH Level Input Voltage (Note 2) | 2.3 V ≤ V _{CC} ≤ 2.7 V | 1.7 | | V |
| | | 2.7 V ≤ V _{CC} ≤ 3.6 V | 2.0 | | |
| V _{IL} | LOW Level Input Voltage (Note 2) | 2.3 V ≤ V _{CC} ≤ 2.7 V | | 0.7 | V |
| | | 2.7 V ≤ V _{CC} ≤ 3.6 V | | 0.8 | |
| V _{OH} | HIGH Level Output Voltage | 2.3 V ≤ V _{CC} ≤ 3.6 V; I _{OH} = -100 μA | V _{CC} - 0.2 | | V |
| | | V _{CC} = 2.3 V; I _{OH} = -8 mA | 1.8 | | |
| | | V _{CC} = 2.7 V; I _{OH} = -12 mA | 2.2 | | |
| | | V _{CC} = 3.0 V; I _{OH} = -18 mA | 2.4 | | |
| | | V _{CC} = 3.0 V; I _{OH} = -24 mA | 2.2 | | |
| V _{OL} | LOW Level Output Voltage | 2.3 V ≤ V _{CC} ≤ 3.6 V; I _{OL} = 100 μA | | 0.2 | V |
| | | V _{CC} = 2.3 V; I _{OL} = 8 mA | | 0.6 | |
| | | V _{CC} = 2.7 V; I _{OL} = 12 mA | | 0.4 | |
| | | V _{CC} = 3.0 V; I _{OL} = 16 mA | | 0.4 | |
| | | V _{CC} = 3.0 V; I _{OL} = 24 mA | | 0.55 | |
| I _{OFF} | Power Off Leakage Current | V _{CC} = 0, V _{IN} = 5.5 V or V _{OUT} = 5.5 V | | 10 | μA |
| I _{IN} | Input Leakage Current | V _{CC} = 3.6 V, V _{IN} = 5.5 V or GND | | ±5 | μA |
| I _{CC} | Quiescent Supply Current | V _{CC} = 3.6 V, V _{IN} = 5.5 V or GND | | 10 | μA |
| ΔI _{CC} | Increase in I _{CC} per Input | 2.3 ≤ V _{CC} ≤ 3.6 V; V _{IH} = V _{CC} - 0.6 V | | 500 | μA |

2. These values of V_I are used to test DC electrical characteristics only.

AC CHARACTERISTICS (t_R = t_F = 2.5 ns; R_L = 500 Ω)

| Symbol | Parameter | Waveform | Limits | | | | | | Units |
|--|---|----------|---------------------------------|------------|-------------------------|------------|---------------------------------|------------|-------|
| | | | T _A = -40°C to +85°C | | | | | | |
| | | | V _{CC} = 3.3 V ± 0.3 V | | V _{CC} = 2.7 V | | V _{CC} = 2.5 V ± 0.2 V | | |
| | | | C _L = 50 pF | | C _L = 50 pF | | C _L = 30 pF | | |
| | | | Min | Max | Min | Max | Min | Max | |
| f _{max} | Clock Pulse Frequency | 1 | 150 | | 150 | | 150 | | MHz |
| t _{PLH} t _{PHL} | Propagation Delay CPn to On or On | 1 | 1.5 1.5 | 7.0 7.0 | 1.5 1.5 | 8.0 8.0 | 1.5 1.5 | 8.4 8.4 | ns |
| t _{PLH} t _{PHL} | Propagation Delay SDn or CDn to On or On | 2 | 1.5 1.5 | 7.0 7.0 | 1.5 1.5 | 8.0 8.0 | 1.5 1.5 | 8.4 8.4 | ns |
| t _s | Setup Time, HIGH or LOW Dn to CPn | 1 | 2.5 | | 2.5 | | 4.0 | | ns |
| t _h | Hold Time, HIGH or LOW Dn to CPn | 1 | 1.5 | | 1.5 | | 2.0 | | ns |
| t _w | CPn Pulse Width, HIGH or LOW SDn or CDn Pulse Width, LOW | 4 | 3.3 3.3 | | 3.3 3.6 | | 4.0 4.0 | | ns |
| t _{rec} | Recovery Time SDn or CDn to CPn | 3 | 2.5 | | 3.0 | | 4.5 | | ns |
| t _{OSSL} t _{OSLH} | Output-to-Output Skew (Note 3) | | | 1.0 1.0 | | | | | ns |

3. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSSL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

MC74LCX74

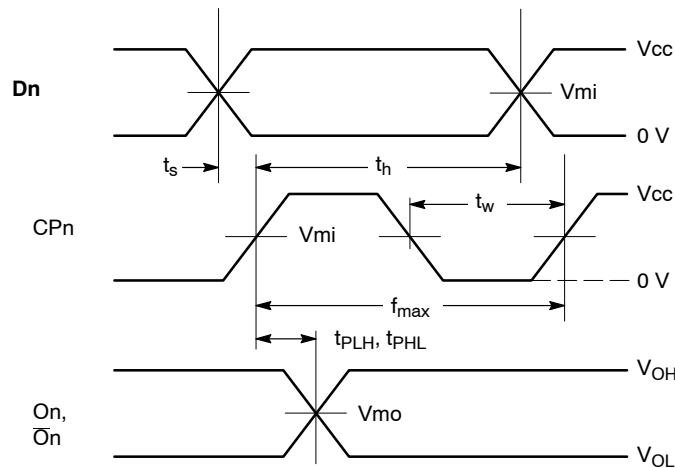
DYNAMIC SWITCHING CHARACTERISTICS

| Symbol | Characteristic | Condition | $T_A = +25^\circ\text{C}$ | | | Units |
|-----------|--|---|---------------------------|------|-----|-------|
| | | | Min | Typ | Max | |
| V_{OLP} | Dynamic LOW Peak Voltage (Note 4) | $V_{CC} = 3.3\text{ V}, C_L = 50\text{ pF}, V_{IH} = 3.3\text{ V}, V_{IL} = 0\text{ V}$ | | 0.8 | | V |
| | | $V_{CC} = 2.5\text{ V}, C_L = 30\text{ pF}, V_{IH} = 2.5\text{ V}, V_{IL} = 0\text{ V}$ | | 0.6 | | V |
| V_{OLV} | Dynamic LOW Valley Voltage (Note 4) | $V_{CC} = 3.3\text{ V}, C_L = 50\text{ pF}, V_{IH} = 3.3\text{ V}, V_{IL} = 0\text{ V}$ | | -0.8 | | V |
| | | $V_{CC} = 2.5\text{ V}, C_L = 30\text{ pF}, V_{IH} = 2.5\text{ V}, V_{IL} = 0\text{ V}$ | | -0.6 | | V |

4. Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

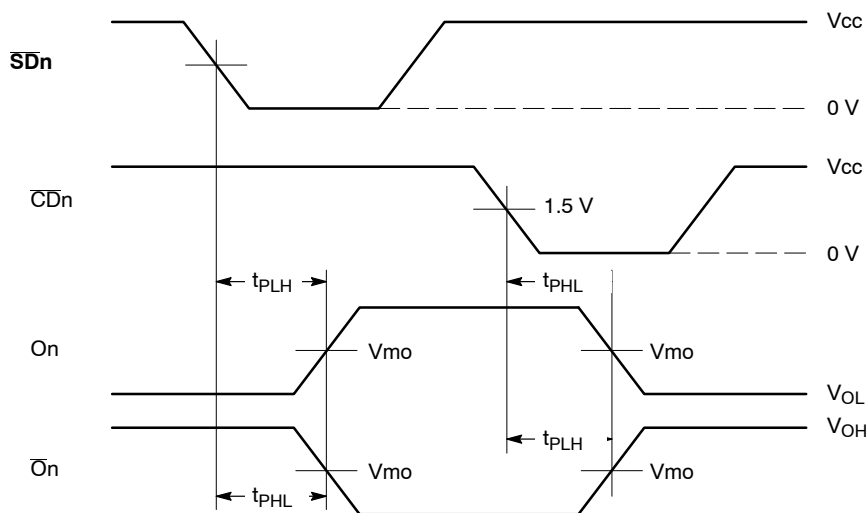
CAPACITIVE CHARACTERISTICS

| Symbol | Parameter | Condition | Typical | Units |
|-----------|-------------------------------|--|---------|-------|
| C_{IN} | Input Capacitance | $V_{CC} = 3.3\text{ V}, V_I = 0\text{ V or } V_{CC}$ | 7 | pF |
| C_{OUT} | Output Capacitance | $V_{CC} = 3.3\text{ V}, V_I = 0\text{ V or } V_{CC}$ | 8 | pF |
| C_{PD} | Power Dissipation Capacitance | 10 MHz, $V_{CC} = 3.3\text{ V}, V_I = 0\text{ V or } V_{CC}$ | 25 | pF |



WAVEFORM 1 - PROPAGATION DELAYS, SETUP AND HOLD TIMES

$t_R = t_F = 2.5\text{ ns}, 10\% \text{ to } 90\%; f = 1\text{ MHz}; t_W = 500\text{ ns}$

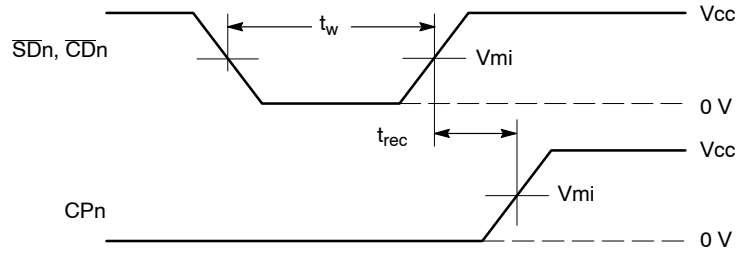


WAVEFORM 2 - PROPAGATION DELAYS

$t_R = t_F = 2.5\text{ ns}, 10\% \text{ to } 90\%; f = 1\text{ MHz}; t_W = 500\text{ ns}$

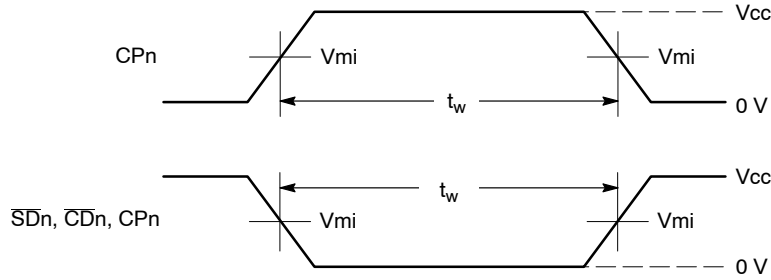
Figure 3. AC Waveforms

MC74LCX74



WAVEFORM 3 - RECOVERY TIME

$t_R = t_F = 2.5$ ns from 10% to 90%; $f = 1$ MHz; $t_w = 500$ ns

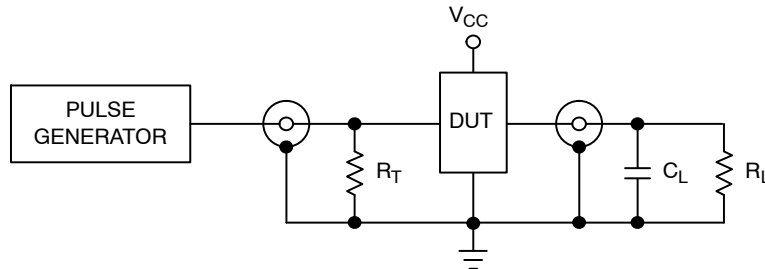


WAVEFORM 4 - PULSE WIDTH

$t_R = t_F = 2.5$ ns (or fast as required) from 10% to 90%;
Output requirements: $V_{OL} \leq 0.8$ V, $V_{OH} \geq 2.0$ V

| Symbol | Vcc | | |
|--------|---------------|-------|---------------|
| | 3.3 V ± 0.3 V | 2.7 V | 2.5 V ± 0.2 V |
| Vmi | 1.5 V | 1.5 V | Vcc/2 |
| Vmo | 1.5 V | 1.5 V | Vcc/2 |

Figure 3. AC Waveforms (Continued)



$C_L = 50$ pF at $V_{CC} = 3.3 \pm 0.3$ V or equivalent (includes jig and probe capacitance)
 $C_L = 30$ pF at $V_{CC} = 2.5 \pm 0.2$ V or equivalent (includes jig and probe capacitance)
 $R_L = R_1 = 500 \Omega$ or equivalent
 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

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SCALE 1:1

SOIC-14 NB
CASE 751A-03
ISSUE L

DATE 03 FEB 2016

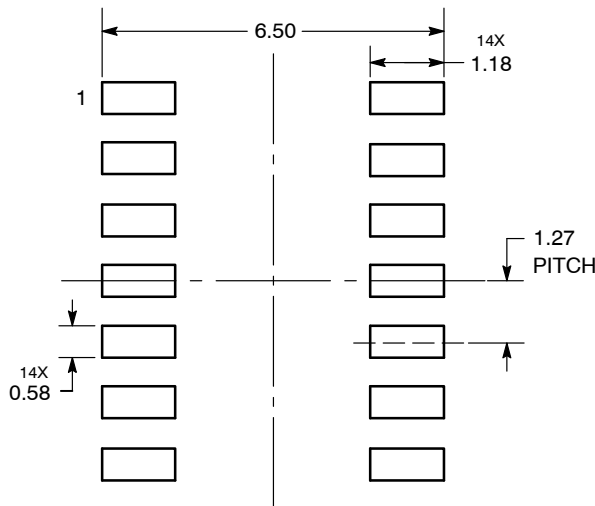


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 1.35 | 1.75 | 0.054 | 0.068 |
| A1 | 0.10 | 0.25 | 0.004 | 0.010 |
| A3 | 0.19 | 0.25 | 0.008 | 0.010 |
| b | 0.35 | 0.49 | 0.014 | 0.019 |
| D | 8.55 | 8.75 | 0.337 | 0.344 |
| E | 3.80 | 4.00 | 0.150 | 0.157 |
| e | 1.27 BSC | | 0.050 BSC | |
| H | 5.80 | 6.20 | 0.228 | 0.244 |
| h | 0.25 | 0.50 | 0.010 | 0.019 |
| L | 0.40 | 1.25 | 0.016 | 0.049 |
| M | 0° | 7° | 0° | 7° |

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

STYLES ON PAGE 2

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SOIC-14
CASE 751A-03
ISSUE L

DATE 03 FEB 2016

STYLE 1:
 PIN 1. COMMON CATHODE
 2. ANODE/CATHODE
 3. ANODE/CATHODE
 4. NO CONNECTION
 5. ANODE/CATHODE
 6. NO CONNECTION
 7. ANODE/CATHODE
 8. ANODE/CATHODE
 9. ANODE/CATHODE
 10. NO CONNECTION
 11. ANODE/CATHODE
 12. ANODE/CATHODE
 13. NO CONNECTION
 14. COMMON ANODE

STYLE 2:
 CANCELLED

STYLE 3:
 PIN 1. NO CONNECTION
 2. ANODE
 3. ANODE
 4. NO CONNECTION
 5. ANODE
 6. NO CONNECTION
 7. ANODE
 8. ANODE
 9. ANODE
 10. NO CONNECTION
 11. ANODE
 12. ANODE
 13. NO CONNECTION
 14. COMMON CATHODE

STYLE 4:
 PIN 1. NO CONNECTION
 2. CATHODE
 3. CATHODE
 4. NO CONNECTION
 5. CATHODE
 6. NO CONNECTION
 7. CATHODE
 8. CATHODE
 9. CATHODE
 10. NO CONNECTION
 11. CATHODE
 12. CATHODE
 13. NO CONNECTION
 14. COMMON ANODE

STYLE 5:
 PIN 1. COMMON CATHODE
 2. ANODE/CATHODE
 3. ANODE/CATHODE
 4. ANODE/CATHODE
 5. ANODE/CATHODE
 6. NO CONNECTION
 7. COMMON ANODE
 8. COMMON CATHODE
 9. ANODE/CATHODE
 10. ANODE/CATHODE
 11. ANODE/CATHODE
 12. ANODE/CATHODE
 13. NO CONNECTION
 14. COMMON ANODE

STYLE 6:
 PIN 1. CATHODE
 2. CATHODE
 3. CATHODE
 4. CATHODE
 5. CATHODE
 6. CATHODE
 7. CATHODE
 8. ANODE
 9. ANODE
 10. ANODE
 11. ANODE
 12. ANODE
 13. ANODE
 14. ANODE

STYLE 7:
 PIN 1. ANODE/CATHODE
 2. COMMON ANODE
 3. COMMON CATHODE
 4. ANODE/CATHODE
 5. ANODE/CATHODE
 6. ANODE/CATHODE
 7. ANODE/CATHODE
 8. ANODE/CATHODE
 9. ANODE/CATHODE
 10. ANODE/CATHODE
 11. COMMON CATHODE
 12. COMMON ANODE
 13. ANODE/CATHODE
 14. ANODE/CATHODE

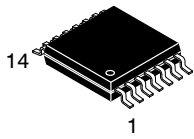
STYLE 8:
 PIN 1. COMMON CATHODE
 2. ANODE/CATHODE
 3. ANODE/CATHODE
 4. NO CONNECTION
 5. ANODE/CATHODE
 6. ANODE/CATHODE
 7. COMMON ANODE
 8. COMMON ANODE
 9. ANODE/CATHODE
 10. ANODE/CATHODE
 11. NO CONNECTION
 12. ANODE/CATHODE
 13. ANODE/CATHODE
 14. COMMON CATHODE

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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



TSSOP-14 WB
CASE 948G
ISSUE C

DATE 17 FEB 2016

SCALE 2:1



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 4.90 | 5.10 | 0.193 | 0.200 |
| B | 4.30 | 4.50 | 0.169 | 0.177 |
| C | --- | 1.20 | --- | 0.047 |
| D | 0.05 | 0.15 | 0.002 | 0.006 |
| F | 0.50 | 0.75 | 0.020 | 0.030 |
| G | 0.65 BSC | | 0.026 BSC | |
| H | 0.50 | 0.60 | 0.020 | 0.024 |
| J | 0.09 | 0.20 | 0.004 | 0.008 |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 |
| K | 0.19 | 0.30 | 0.007 | 0.012 |
| K1 | 0.19 | 0.25 | 0.007 | 0.010 |
| L | 6.40 BSC | | 0.252 BSC | |
| M | 0° | 8° | 0° | 8° |

GENERIC MARKING DIAGRAM*

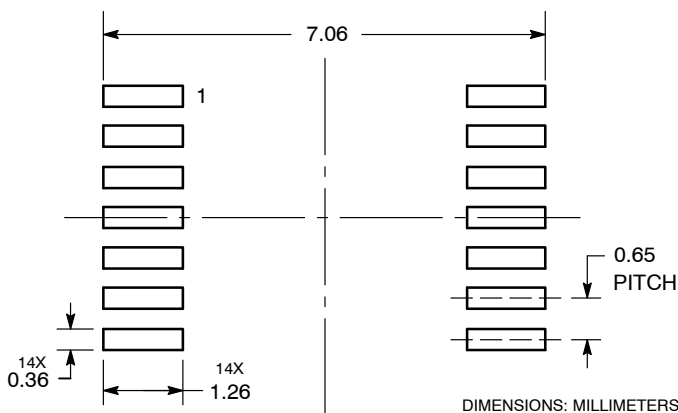


- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

SOLDERING FOOTPRINT



| | | |
|-------------------------|--------------------|--|
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